

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.30618	100.0	4.6
			Subtotal	0.30618	100	4.6
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.0266	10.0	0.39963
	Silver alloy	Silver (Ag)	7440-22-4	0.00532	2.0	0.07993
	Lead alloy	Lead (Pb)	7439-92-1	0.23408	88.0	3.51675
			Subtotal	0.266	100	3.99631
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02572	100.0	0.38648
			Subtotal	0.02572	100	0.38648
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00978	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00652	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00978	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03586	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.539	99.81	488.8594
			Subtotal	32.60094	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34392	100.0	5.167
			Subtotal	0.34392	100	5.167
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.31658	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.83036	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.4652	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19937	0.3	2.99532
	Polymer	Epoxy resin system		6.64572	10.0	99.844
			Subtotal	66.45723	100	998.44
			Total	99.99999	100	1502.3798

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